



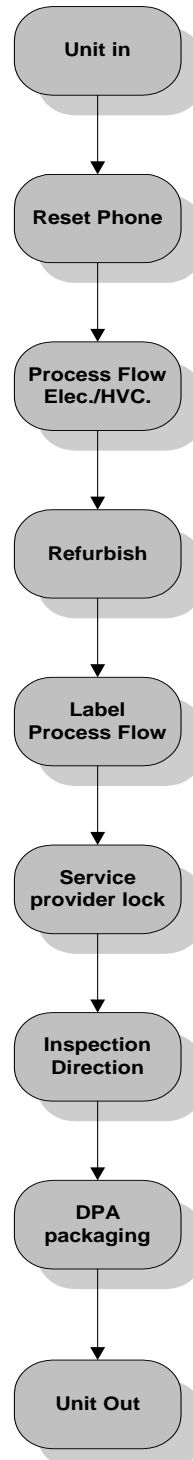
Process Flow, Swap

Applicable for C702, C702a & C702c

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1 Process Flow



1.1 Explanation of the process steps

| Box | Reference |
|--------------------------|---|
| Reset phone | Working Instruction, Build Swap – For reset of the customer's parameters in the phone, use the Master Reset function in the phone software as specified in the Working instructions. Continue with Repair Flow Std./ Adv. |
| Process Flow Elec. /HVC. | Process Flow, Electrical or HVC. - Repair the faulty unit according to the directives for the Electrical or HVC repair process. Continue with Refurbish. |
| Refurbish | Refurbish – All Swap units need to have new looking plastics as front cover, frame, keyboard etc. (this should be done when assembling the unit after repair). Continue with Process Flow, Label. |
| Process Flow, Label | Process Flow, Label. - All exchange units must be labelled according to the instructions for the Label Process Continue with Service Provider Lock test. |
| Service Provider Lock | Service Provider Lock. – Check the service provider lock. Continue with Cosmetic Inspection. |
| Inspection Direction | Inspection Direction, Build Swap. - A swap unit must be inspected according to the instructions and templates. When inspecting a complete unit, one should start with the following issues; dust in the display area, the label should be applied straight and have a good printing quality and the unit must be free from fingerprints, stains, oil, grease and other faults deterring the neat impression. Continue with DPA-packaging. |
| DPA-packaging | Working Instruction, Build Swap. - Pack the DPA according to the instruction. |

2 Revision history

| Rev. | Date | Changes / Comments |
|------|------------|--------------------|
| 1 | 2008-05-22 | First Release |